

Modular Building Blocks

Infinite Possibility Awaits



Modular Design to Create Multiple Systems

Ingrasys develops a game-changing approach to break down the legacy servers into reusable modular components, and mix and match them to build up multiple new systems. This approach creates unlimited possibilities and allows for future scalability across different generations of platforms.

One Module, Maximum Flexibility

Reuse the modules as much as possible. When the system needs to be updated, only replace one module with a new one with no other changes required.

Support Enterprise EIA 19" and ORv3 Racks

Use the same modular components differently to configure systems respectively for Enterprise EIA 19" rack and Open Compute ORv3 rack.

Rack-integrated Liquid Cooling Solution

Ingrasys OCP-compliant server supports liquid cooling technology to provide higher cooling efficiency, which allows high-power CPU and GPU to run at their full performance while reducing significant energy consumption.



Truly Flexible Systems



Customized Modules



Faster Time-to-Market Solution



Easy Future Scalability



Air & Liquid Cooling Solutions

Modular Building Blocks

Modules

HPM

Develop one HPM for each CPU family to simply hardware design to a minimum extent

Drive Cages & Interposers

Support different combinations of drive form factors and CXL memory modules for maximum flexibility and memory expansion

DC-SCM

Develop one DC-SCM – a security and management module – to be used across different HPMs or build a customized DC-SCM to meet specific needs

Functional Plug-in Cards

Install PCIe CEM card modules and OCP NIC to realize different high-speed I/O functions



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SV1120A

Specifications



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Storage

- **SKU 1:** 24 x E1.S SSDs
- **SKU 2:** 12 x U.2 NVMe SSDs
- **SKU 3:** 16 x E1.S SSDs
- **SKU 4:** 8 x U.2 NVMe SSDs
- 2 x 22110 M.2 Boot Drives



Memory

- 24 x DDR5 RDIMMs, up to 4800 MT/s at 1DPC
- 2 x E3.S CXL Memory Modules (SKU 3 & 4)



Expansion Slots

- 2 x PCIe 5.0 x16 FHHL Slots
- 1 x PCIe 5.0 x16 OCP NIC 3.0



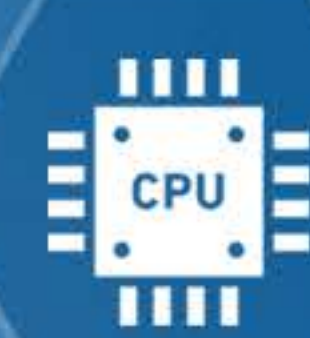
I/O Ports

- 1 x 1GbE/RJ45 Management Port
- 1 x USB 2.0
- 1 x Mini Display Port
- 1 x Reset Button
- 1 x Power Button with LED
- 1 x UID Button with LED



Form Factor

1 RU



Processor

2 x 4th Gen AMD EPYC™ Server Processors



HPM/Motherboard

AMD SP5 Platform



PSUs

2 x 2400W Platinum
Redundant (1+1) PSU



Chassis Dimensions (H x W x D)

1.71" x 17.32" x 31.8" /
43.4mm x 440.0mm x 807.8mm



Security & Management

DC-SCM 1.0 (Root of Trust, TPM,
AST2600 BMC)



Cooling Solution

8 x 4056 Dual Rotor System Fans
(N+1 Redundant)



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Specifications



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Storage

- **SKU 1:** 12 x E1.S SSDs
- **SKU 2:** 6 x E1.S SSDs
- **SKU 3:** 6 x E1.S SSDs
- 2 x 22110 M.2 Boot Drives



Memory

- 24 x DDR5 RDIMMs, up to 4800 MT/s at 1DPC
- 2 x E3.S CXL Memory Modules (SKU 3)



Expansion Slots

- **SKU 1 & 3:** 2 x PCIe 5.0 x16 FHHL Slots
1 x PCIe 5.0 x16 OCP NIC 3.0
- **SKU 2:** 2 x PCIe 5.0 x16 FHHL Slots
2 x PCIe 5.0 x16 LP/HHHL with Riser Card Slots
1 x PCIe 5.0 x16 OCP NIC 3.0



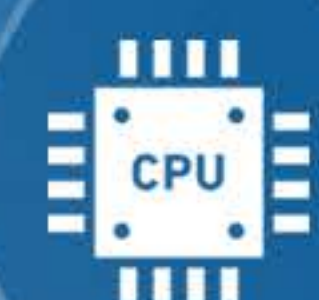
I/O Ports

- 1 x 1GbE/RJ45 Management Port
- 1 x USB 2.0
- 1 x Mini Display Port
- 1 x Reset Button
- 1 x Power Button with LED
- 1 x UID Button with LED



Form Factor

1 OU



Processor

2 x 4th Gen AMD EPYC™ Server Processors



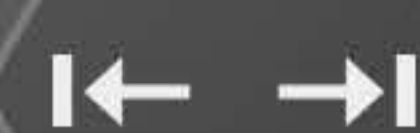
HPM/Motherboard

AMD SP5 Platform



PSUs

Centralized 48V Bus Bar with PDB



Chassis Dimensions (H x W x D)

1.83" x 20.47" x 31.4" /
46.5mm x 520.0mm x 798.0mm



Security & Management

DC-SCM 1.0 (Root of Trust, TPM, AST2600 BMC)



Cooling Solution

- **Air:** CPU Remote Heatsink, 11 x 4056 Dual Rotor System Fans (N+1 Redundant)
- **Liquid:** CPU Cold-Plates to Rack Quick-Disconnects, 6 x 4056 Dual Rotor System Fans (N+1 Redundant)



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